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(54) **CAMERA MODULE PACKAGING
STRUCTURE AND ELECTRONIC DEVICE
HAVING THE SAME**

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(57) **ABSTRACT**
A camera module packaging structure with simplified process, and an electronic device carrying it, includes a FPC, an ACF, an embedded printed circuit board, a no-flow underfill, and a chip-scale package camera module. The present application uses a no-flow underfill, which can omit steps of applying the flux and removing the flux, thus the process is simplified. By setting the ACF in the present application, a stable structure having vertical conduction characteristic and horizontal insulation characteristic is formed between the chip-scale packaged camera module and the flexible circuit board.

